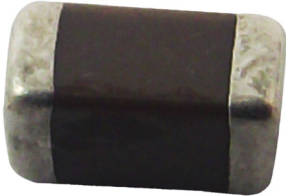


**RoHS
Compliant**



Description:

WTC middle and high voltage series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords increased capacitance values in a given case size and voltage rating.

WTC capacitor arrays are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

Features:

- High density mounting due to mounting space saving
- Mounting cost saving.
- Increased throughput.

Applications:

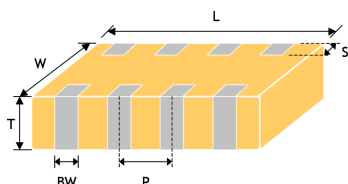
- For use as a bypass for digital and analog signal line noise
- Computer motherboards and peripherals.
- The other common electronic circuits.

How To Order:

MCY	4C	3	B	103	K	500	C	T
<u>Series</u>	<u>Cap. Nr.</u>	<u>Termination Pitch</u>	<u>Dielectric</u>	<u>Capacitance</u>	<u>Tolerance</u>	<u>Rated voltage</u>	<u>Termination</u>	<u>Packaging</u>
Multicomp Y=Capacitor array	4C=4xCap	3=0.03" pitch* 2=0.02" pitch*	N=NP0 (C0G) B=X7R F=Y5V	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 103=10x10 ³ =10,000pF =10nF	J=±5% K=±10% M=±20% Z=- 20/+80%	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 100=10V DC 160=16V DC 250=25V DC 500=50V DC 101=100V DC	C=Cu/Ni/Sn	T=7" reeled
Y4C3: 4x0603 (0612) Y4C2: 4x0402 (0508)								

Size/ Inch (mm) : 4x0402=0508 (1220), 4x0603=0612 (1632)

External Dimensions:



The outline of MLCC

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol	S (mm)	BW (mm)	P (mm)
4x0402 0508 (1220)	2 ±0.15	1.25 ±0.15	0.85 ±0.1 T	0.2 ±0.1	0.25 ±0.1	0.5 ±0.1
4x0603 0612 (1632)	3.2 ±0.15	1.6 ±0.15	0.8 ±0.1 B	0.3 ±0.2	0.4 ±0.15	0.8 ±0.15

General Electrical Data:

Dielectric	NP0		X7R		Y5V
Size Inch (mm)	4x0402 0508 (1220)	4x0603 0612 (1632)	4x0402 0508 (1220)	4x0603 0612 (1632)	4x0603 0612 (1632)
Capacitance*	10pF to 270pF	10pF to 470pF	1000pF to 100nF	180pF to 100nF	10nF to 100nF
Capacitance tolerance**	J (±5%), K (±10%)		K (±10%), M (±20%)		Z (-20/+80%)
Rated voltage (WVDC)	25, 50V, 100V		10V, 16V, 25V, 50V	16V, 25V, 50V	16V, 50V
Q/Tan δ*	Cap<30pF: Q≥400+20C Cap≥30pF: Q≥1000		Ur=50V, ≤2.5% Ur=25V&16V, ≤3.5% Ur=10V, ≤5.0%		Ur=50V, ≤5% Ur=16V, ≤7%
Insulation resistance at Ur	≥10GΩ		≥10GΩ or RxC≥500ΩxF whichever is less		
Operating temperature	-55 to +125°C				-25 to +85°C
Capacitance characteristic	±30ppm		±15%		+30/-80%
Termination	Ni/Sn (lead-free termination)				

* Measured at the condition of 30~70% related humidity.

NP0: Apply 1 ±0.2Vrms, 1MHz ±10% for Cap≤1,000pF and 1 ±0.2Vrms, 1kHz ±10% for Cap>1,000pF, 25°C at ambient temperature

X7R, X5R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25°C ambient temperature.

Y5V: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 20°C ambient temperature.

** Preconditioning for Class II MLCC : Perform a heat treatment at 150 ±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.

Packaging Dimension And Quantity:

Size Inch (mm)	Thickness/Symbol (mm)		Paper tape	
			7" reel	13" reel
4x0402 0508 (1220)	0.85±0.10	T	4k	-
4x0603 0612 (1632)	0.80±0.10	B	4k	-

Unit : pieces

Reliability Test Conditions and Requirements:

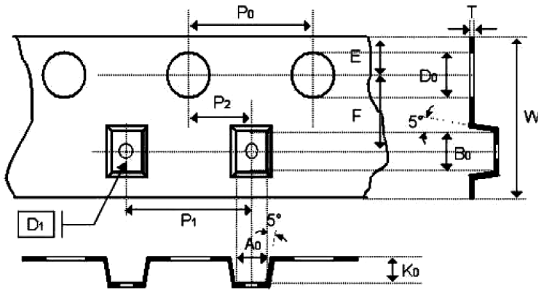
No	Item	Test Condition	Requirements
1	Visual and Mechanical	-	No remarkable defect. Dimensions to conform to individual specification sheet.
2	Capacitance	Class I: (NP0)	Shall not exceed the limits given in the detailed spec.
3	Q/ D.F. (Dissipation Factor)	Class II: (X7R, Y5V) 1.0±0.2Vrms, 1MHz±10% 1.0±0.2Vrms, 1kHz±10%	NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C X7R: Ur=50V, ≤2.5%; Ur=25V&16V, ≤3.5%; Ur=10V, ≤5.0% Y5V: Ur=50V, ≤5%; Ur=16V, ≤7%

No	Item	Test Condition	Requirements																
4	Dielectric Strength	To apply 250% rated voltage. Duration: 1 to 5 sec. Charge and discharge current less than 50mA.	No evidence of damage or flash over during test.																
5	Insulation Resistance	To apply rated voltage for max. 120 sec.	$\geq 10G\Omega$ or $RxC \geq 500\Omega \cdot F$ whichever is smaller.																
6	Temperature Coefficient	With no electrical load. <table border="1" data-bbox="359 705 702 851"> <thead> <tr> <th>T.C.</th> <th>Operating Temp</th> </tr> </thead> <tbody> <tr> <td>NP0</td> <td>55~125°C at 25°C</td> </tr> <tr> <td>X7R</td> <td>55~125°C at 25°C</td> </tr> <tr> <td>Y5V</td> <td>25~85°C at 20°C</td> </tr> </tbody> </table>	T.C.	Operating Temp	NP0	55~125°C at 25°C	X7R	55~125°C at 25°C	Y5V	25~85°C at 20°C	<table border="1" data-bbox="805 683 1204 840"> <thead> <tr> <th>T.C.</th> <th>Capacitance Change</th> </tr> </thead> <tbody> <tr> <td>NP0</td> <td>Within ± 30ppm/°C</td> </tr> <tr> <td>X7R</td> <td>Within $\pm 15\%$</td> </tr> <tr> <td>Y5V</td> <td>Within $+30\%/-80\%$</td> </tr> </tbody> </table>	T.C.	Capacitance Change	NP0	Within ± 30 ppm/°C	X7R	Within $\pm 15\%$	Y5V	Within $+30\%/-80\%$
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NP0	Within ± 30 ppm/°C																		
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Y5V	Within $+30\%/-80\%$																		
7.	Adhesive Strength of Termination	Pressurizing force: 5N (≤ 0603) and 10N (> 0603) Test time: 10 ± 1 sec.	No remarkable damage or removal of the terminations.																
8	Vibration Resistance	Vibration frequency: 10~55 Hz/min. Total amplitude: 1.5mm Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) Measurement to be made after keeping at room temp. for 24 ± 2 hrs.	No remarkable damage. Cap change and Q/D.F.: To meet initial spec.																
9	Solderability	Solder temperature: $235 \pm 5^\circ C$ Dipping time: 2 ± 0.5 sec.	95% min. coverage of all metalized area																
10	Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1mm per second until the deflection becomes 1mm and then the pressure shall be maintained for 5 ± 1 sec. Measurement to be made after keeping at room temp. for 24 ± 2 hrs.	No remarkable damage. Cap change: NP0: within $\pm 5\%$ or $\pm 0.5pF$ whichever is larger. X7R: within $\pm 12.5\%$ Y5V: within $\pm 30\%$ (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)																
11	Resistance to Soldering Heat	Solder temperature: $260 \pm 5^\circ C$ Dipping time: 10 ± 1 sec Preheating: 120 to $150^\circ C$ for 1 minute before immerse the capacitor in a eutectic solder. Before initial measurement (Class II only): Perform $150+0/-10^\circ C$ for 1 hr and then set for 24 ± 2 hrs at room temp. Measurement to be made after keeping at room temp. for 24 ± 2 hrs.	No remarkable damage. Cap change: NP0: within $\pm 5.0\%$ or $\pm 0.5pF$ whichever is larger. X7R: within $\pm 12.5\%$ Y5V: within $\pm 30\%$ Q/D.F., I.R. and dielectric strength: To meet initial requirements. 25% max. leaching on each edge.																

No	Item	Test Condition	Requirements															
12	Temperature Cycle	<p>Conduct the five cycles according to the temperatures and time.</p> <table border="1"> <thead> <tr> <th>Step</th> <th>Temp. (°C)</th> <th>Time (min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>Min. operating temp. +0/-3</td> <td>30±3</td> </tr> <tr> <td>2</td> <td>Room temp.</td> <td>2~3</td> </tr> <tr> <td>3</td> <td>Max. operating temp. +3/-0</td> <td>30±3</td> </tr> <tr> <td>4</td> <td>Room temp.</td> <td>2~3</td> </tr> </tbody> </table> <p>Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs.</p>	Step	Temp. (°C)	Time (min.)	1	Min. operating temp. +0/-3	30±3	2	Room temp.	2~3	3	Max. operating temp. +3/-0	30±3	4	Room temp.	2~3	<p>No remarkable damage. Cap change: NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements.</p>
Step	Temp. (°C)	Time (min.)																
1	Min. operating temp. +0/-3	30±3																
2	Room temp.	2~3																
3	Max. operating temp. +3/-0	30±3																
4	Room temp.	2~3																
13	Humidity (Damp Heat) Steady State	<p>Test temp.: 40±2°C Humidity: 90~95% RH Test time: 500+24/-0hrs. Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp Measurement to be made after keeping at room temp. for 24±2 hrs.</p>	<p>No remarkable damage. Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% Q/D.F. value: NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C Cap<10pF; Q≥200+10C X7R: ≤3.0% Y5V: ≤7.5% I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.</p>															
14	Humidity (Damp Heat) Load	<p>Test temp.: 40±2°C Humidity: 90~95%RH Test time: 500+24/-0 hrs. To apply voltage : rated voltage Before initial measurement (Class II only): To apply test voltage for 1hr at 40°C and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs.</p>	<p>No remarkable damage. Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% Q/D.F. value: NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C X7R: ≤3.0% Y5V: ≤7.5% I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller.</p>															
15	High Temperature Load (Endurance)	<p>Test temp.: NP0, X7R: 125±3°C Y5V: 85±3°C To apply voltage: 200% of rated voltage. Test time: 1000+24/-0 hrs. Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs</p>	<p>No remarkable damage. Cap change: NP0: within ±3.0% or ±0.3pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% Q/D.F. value: NP0: Cap≥30pF, Q≥350 10pF≤Cap<30pF, Q≥275+2.5C Cap<10pF, Q≥200+10C X7R: ≤3.0% Y5V: ≤7.5% I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.</p>															

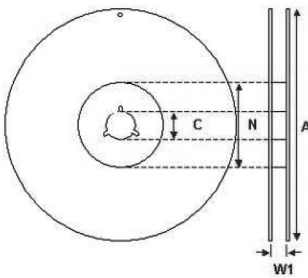
Appendixes

Tape & Reel Dimensions



The dimension of plastic tape

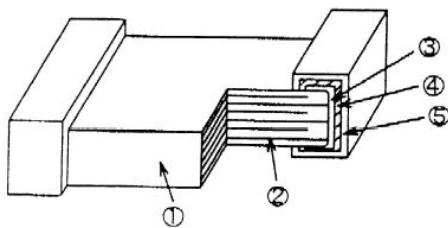
Size Inch (mm)	4x0402 0508 (1220)	4x0603 0612 (1632)
Thickness	T	B
A ₀	1.5 ±0.1	2 ±0.1
B ₀	2.3 ±0.1	3.5 ±0.1
T	0.95 ±0.05	0.95 ±0.05
K ₀	-	-
W	8 ±0.1	8 ±0.1
P ₀	4 ±0.1	4 ±0.1
10xP ₀	40 ±0.1	40 ±0.1
P ₁	4 ±0.1	4 ±0.1
P ₂	2 ±0.05	2 ±0.05
D ₀	1.55 ±0.05	1.5 ±0.05
D ₁	-	-
E	1.75 ±0.05	1.75 ±0.1
F	3.5 ±0.05	3.5 ±0.05



The dimension of reel

Reel size	7"
C	13 +0.5/-0.2
W1	8.4 +1.5/-0
A	178 ±0.10
N	60 +1/-0

Constructions:



No.	Name	NP0, X7R, Y5V
1	Ceramic material	BaTiO ₃ based
2	Inner electrode	Ni
3	Termination	Inner layer
4		Middle layer
5		Outer layer
		Sn (Matt)

Storage and handling conditions

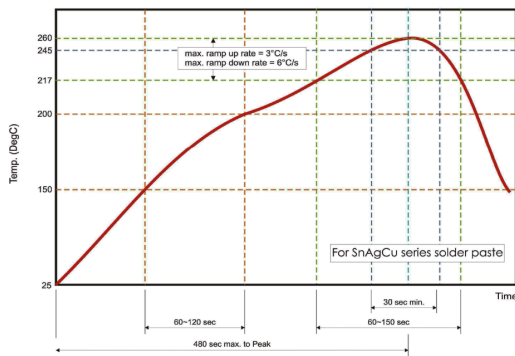
- (1) To store products at 5°C to 40°C ambient temperature and 20 to 70% related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

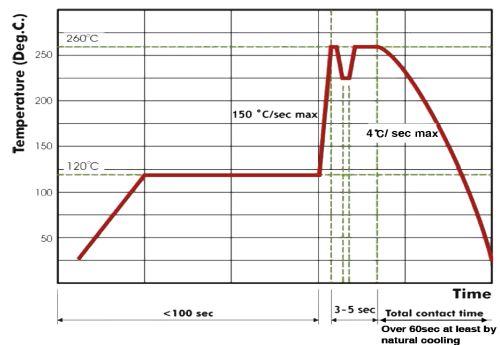
- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended Soldering Conditions:

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.



Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.



Recommended wave soldering profile for SMT process with SnAgCu series solder.

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